Parameter	Symbol	Rating	Unit
Drain–Source Voltage	V_{DSS}	-60	V
Gate–Body Leakage Voltage	V_{GSS}	±20	V
Drain Current - Continuous	I_D	-5	A
Pulsed Drain Current	I_{DM}	-18	A
Power Dissipation (Surface Mounted on FR4 Board, t ≤ 10 sec.)	P_D	1.5	W
Operating and Storage Temperature Range	T_J,T_{STG}	-55 150	
Maximum Junction-to-Ambient t ≤ 10s	$R_{\theta JA}$		

/ Electrical Characteristic Curve

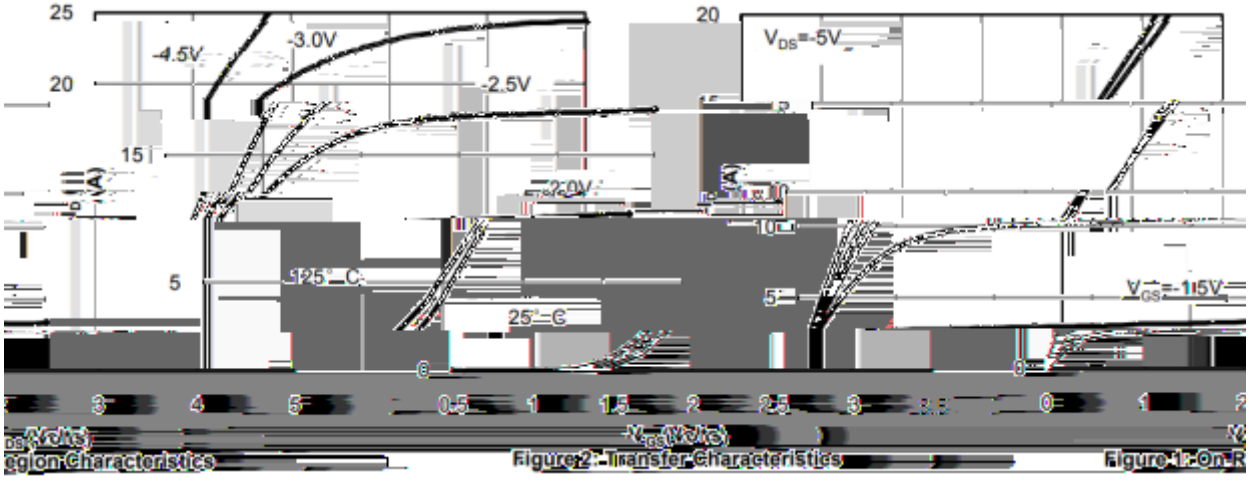
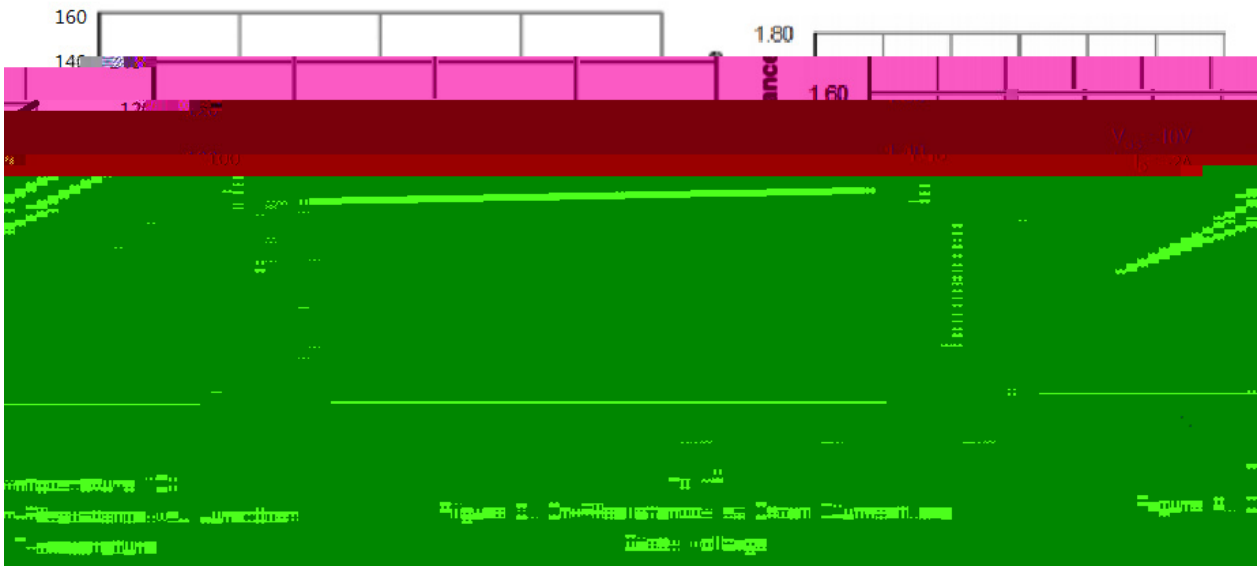


Figure 2. Transfer Characteristics



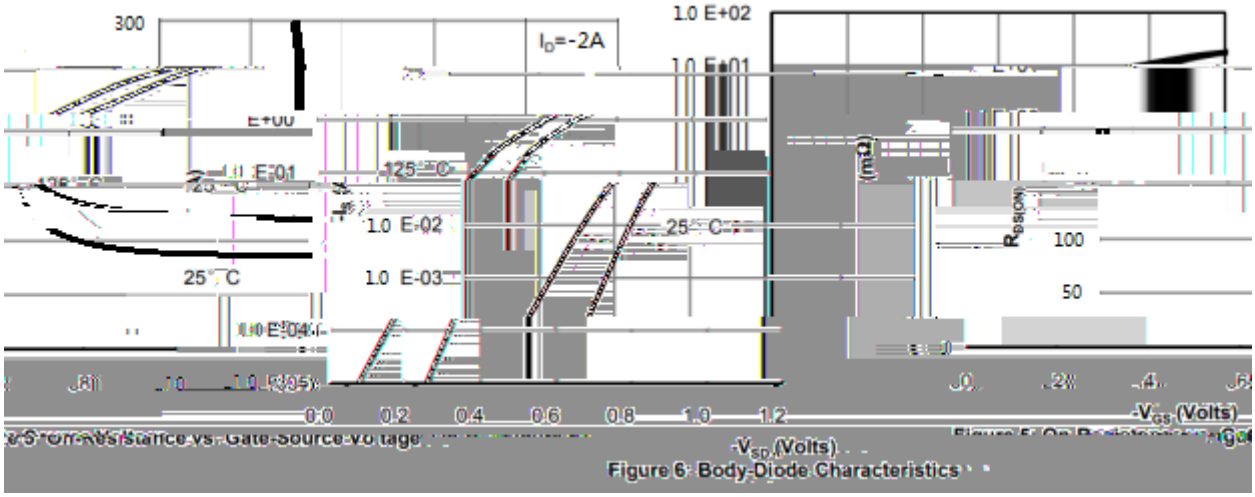
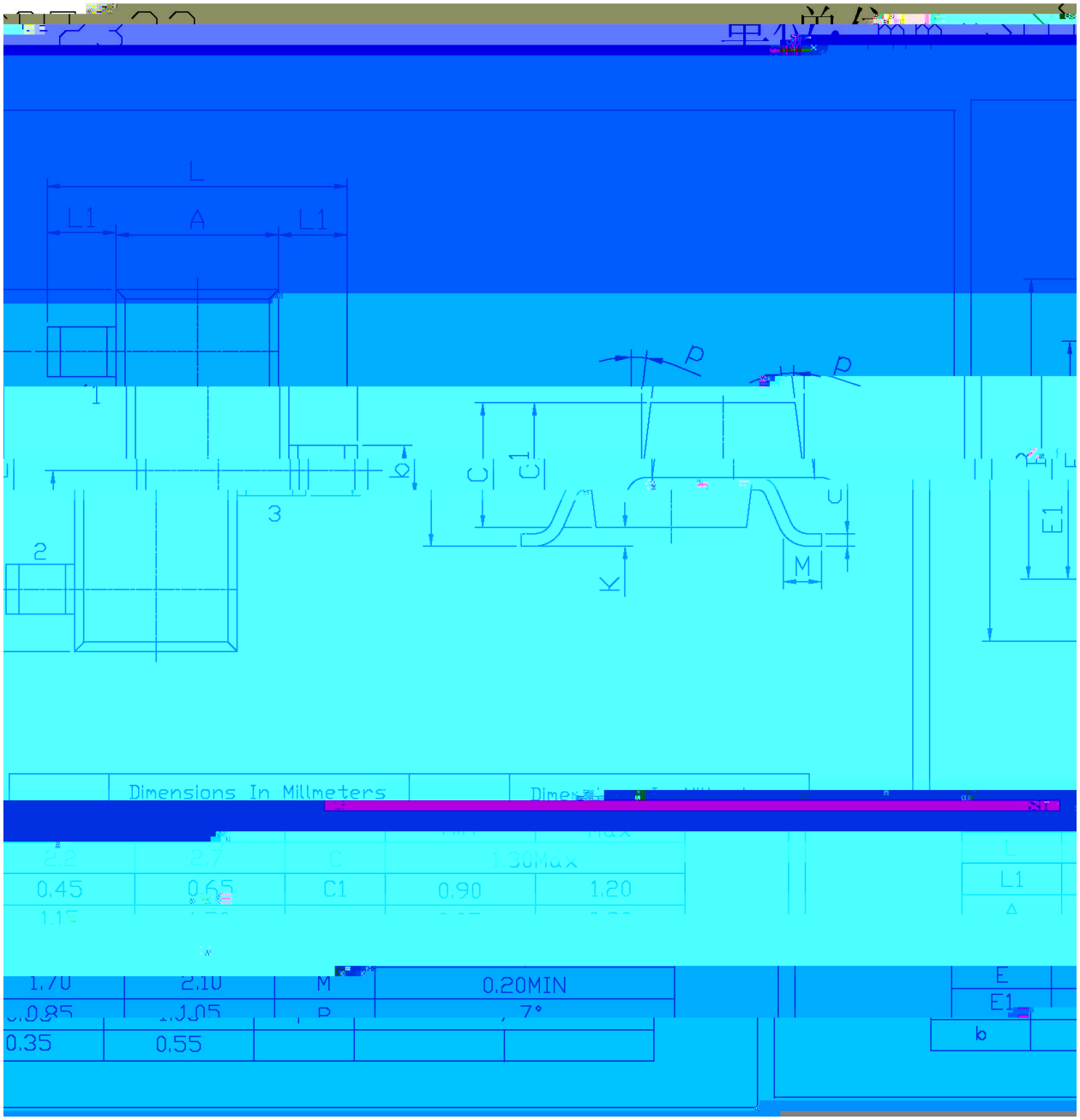
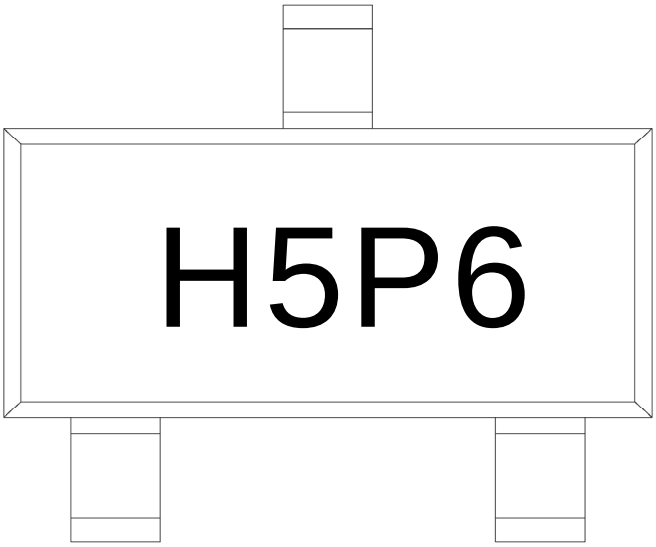


Figure 6. Body-Diode Characteristics

/ Package Dimensions



/ Marking Instructions



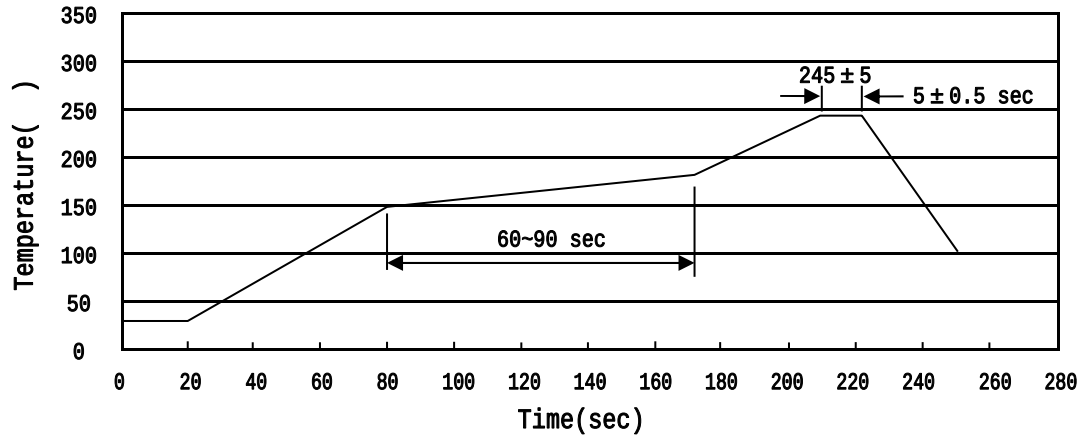
H:

5P6

Note:

H	Company Code
5P6:	Product Type

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



1		150	180		60	90sec;	
2		245±5				5±0.5sec;	
3				2	10	/sec.	

Note:

1.Preheating:150~180 , Time:60~90sec.

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm³)

/ Notices